Global 3D IC & 2.5D IC Packaging Market Growth 2025-2031

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Abstracts

The global 3D IC & 2.5D IC Packaging market size is predicted to grow from US$ 10530 million in 2025 to US$ 27610 million in 2031; it is expected to grow at a CAGR of 17.4% from 2025 to 2031.

The impact of the latest U.S. tariff measures and the corresponding policy responses from countries worldwide on market competitiveness, regional economic performance, and supply chain configurations will be comprehensively evaluated in this report.

A three-dimensional integrated circuit (3D IC) is a package with multiple layers of silicon wafers stalked together, along with electronic components using through-silicon vias (TSVs),while a 2.5-dimensional integrated circuit (2.5D IC) is a package with an active electronic components (for example, a die or a chip) stacked on an interposer through conductive bumps or TSVs.

The Global 3D IC & 2.5D IC Packaging Market is poised to grow strong during the forecast period 2017 to 2027. Some of the prominent trends that the market is witnessing include increasing demand for high-end computing, servers, and data centers, rising demand for smartphones, tablets, and gaming devices and recent technological developments in 3D IC & 2.5D IC packaging.

LP Information, Inc. (LPI) ' newest research report, the “3D IC & 2.5D IC Packaging Industry Forecast” looks at past sales and reviews total world 3D IC & 2.5D IC Packaging sales in 2024, providing a comprehensive analysis by region and market sector of projected 3D IC & 2.5D IC Packaging sales for 2025 through 2031. With 3D IC & 2.5D IC Packaging sales broken down by region, market sector and sub-sector, this report provides a detailed analysis in US$ millions of the world 3D IC & 2.5D IC

Packaging industry.

This Insight Report provides a comprehensive analysis of the global 3D IC & 2.5D IC Packaging landscape and highlights key trends related to product segmentation, company formation, revenue, and market share, latest development, and M&A activity. This report also analyzes the strategies of leading global companies with a focus on 3D IC & 2.5D IC Packaging portfolios and capabilities, market entry strategies, market positions, and geographic footprints, to better understand these firms' unique position in an accelerating global 3D IC & 2.5D IC Packaging market.

This Insight Report evaluates the key market trends, drivers, and affecting factors shaping the global outlook for 3D IC & 2.5D IC Packaging and breaks down the forecast by Type, by Application, geography, and market size to highlight emerging pockets of opportunity. With a transparent methodology based on hundreds of bottom-up qualitative and quantitative market inputs, this study forecast offers a highly nuanced view of the current state and future trajectory in the global 3D IC & 2.5D IC Packaging.

This report presents a comprehensive overview, market shares, and growth opportunities of 3D IC & 2.5D IC Packaging market by product type, application, key manufacturers and key regions and countries.

Segmentation by Type:

3D TSV

2.5D and 3D Wafer-Level Chip-Scale Packaging (WLCSP)

Segmentation by Application:

Automotive

Consumer electronics

Medical devices

Military & aerospace

Telecommunication

- Industrial sector and smart technologies

This report also splits the market by region:

- Americas
  - United States
  - Canada
  - Mexico
  - Brazil
- APAC
  - China
  - Japan
  - Korea
  - Southeast Asia
  - India
  - Australia
- Europe
  - Germany
  - France
  - UK
  - Italy

- Russia

Middle East & Africa

- Egypt
- South Africa
- Israel
- Turkey
- GCC Countries

The below companies that are profiled have been selected based on inputs gathered from primary experts and analysing the company's coverage, product portfolio, its market penetration.

- Intel Corporation
- Toshiba Corp
- Samsung Electronics
- Stmicroelectronics
- Taiwan Semiconductor Manufacturing
- Amkor Technology
- United Microelectronics
- Broadcom
- ASE Group
- Pure Storage

Advanced Semiconductor Engineering

JCET

TongFu Microelectronics

Key Questions Addressed in this Report

What is the 10-year outlook for the global 3D IC & 2.5D IC Packaging market?

What factors are driving 3D IC & 2.5D IC Packaging market growth, globally and by region?

Which technologies are poised for the fastest growth by market and region?

How do 3D IC & 2.5D IC Packaging market opportunities vary by end market size?

How does 3D IC & 2.5D IC Packaging break out by Type, by Application?

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